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VIA Unveils New 0.13 Micron Version VIA C3(tm) Processor at Computex Taipei 2001

Expands into notebook market segment with the launch of the new VIA C3(tm) Mobile Processor

Taipei, Taiwan, 5 June 2001 - VIA Technologies, Inc today announced the introduction of the latest version of the VIA C3(tm) processor at Computex Taipei 2001. Formerly known by its codename of Ezra, new VIA C3(tm) is the first processor in the world to go into volume production using a leading-edge 0.13 micron process, ensuring higher levels of performance and enhanced power consumption and thermal dissipation properties.

At the same time, VIA also unveiled the new mobile VIA C3(tm) processor, which leverages the world's smallest x86 die size and a highly efficient architecture to deliver the best balance of performance and power consumption for all mobile market segments.

Debuting at speeds ranging up to 800MHz, the mobile VIA C3(tm) processor is available in a choice of PGA, micro PGA, and EBGA package types that are fully compatible with the existing socket infrastructure to ensure easy integration and rapid time to market for OEMs and notebook vendors. An ultra low voltage version of the processor that reduces power consumption to less than one watt or ultra slim and mini notebook designs is also available.

"The launch of the new mobile VIA C3(tm) processor builds on our leadership position in the mobile core logic chipset and graphics markets," commented Wenchi Chen, President and CEO, VIA Technologies, Inc. "It enables us to provide our customers with the industry's richest platform of low power, high performance solutions for a complete range of full featured, slim and light, and mini-note notebooks covering all market segments."

"TSMC has invested significant resources in bringing our high-performance 0.13 micron process to market," said Dr. FC Tseng, president of TSMC. "That such a strategic customer as VIA will leverage the benefits of our world-leading technology for its next generation of processors, speaks volumes for this accomplishment. We are committed to providing them with the highest quality manufacturing support available."

"The new VIA C3(tm) processor adopts the PGA, EBGA and flip-chip interconnect technologies offered by ASE Group to optimize the processor's electrical performance," added J.J. Lee, Vice

President R&D at ASE. "The utilization of our ceramic substrates also ensures the processor's excellent thermal performance. ASE masters the innovative technologies needed to fulfill the requirements of high-level CPU packaging. In the future, we will continue to provide superior quality packaging services to VIA."

Mobile VIA C3(tm) Processor

The mobile VIA C3(tm) processor is shipping now at speeds up to 800MHz; pricing information is available on request. Certain versions also come with VIA LongHaul(tm) power management technology, which can reduce the processor's voltage and clock speed to maximize battery life. Other features include 128KB Level 1 and 64KB Level 2 full speed cache, as well as support for a 100/133MHz Front Side Bus and MMX(tm) and 3DNow! multimedia instructions, to ensure robust levels of performance for all the most popular mainstream software and Internet applications.